## **EUROPEAN PATENT OFFICE**

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APPLICANT: SHARP CORP;

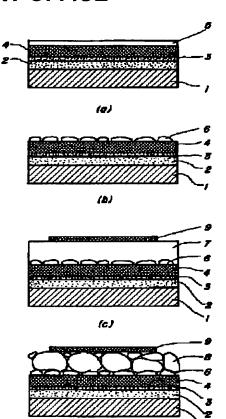
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H01L 27/108 H01L 21/8242 H01L 21/8247 H01L 29/788 H01L 29/792

TITLE : SEMICONDUCTOR STORAGE

**ELEMENT MANUFACTURING METHOD** 



(d)

ABSTRACT :

PROBLEM TO BE SOLVED: To obtain a ferroelectric film of a dense crystal structure, capable of forming a ferroelectric film of dense crystal structure on the surface of a lower electrode, even in a Bi-layered structure compound, in which coarsened crystal grains are easily generated by separating crystallization steps into a plurality of stages.

SOLUTION: A Ti adhesive layer 3 and then a lower Pt electrode 4 are formed on a silicon substrate 1, having a silicon oxide film 2 formed by thermal oxidation. Next, on the lower Pt electrode 4, a layer of an MOD solution of  $SrBi_2Ta_2O_9$  is coated. After having been subjected to a dry step, the  $SrBi_2Ta_2O_9$  film is crystallized by a heat treatment at a substrate temperature of  $600^{\circ}C$  under a reduced pressure and oxygen atmosphere. Thereafter, coating and drying steps are repeatedly conducted three times on the  $SrBi_2Ta_2O_9$  film 6 to provide the  $SrBi_2Ta_2O_9$  film 6 with a desired film thickness by the MOD method and to turn the film 6 into an amorphous or microcrystal state by heat treatment. After an upper Pt electrode 9 is formed on the  $SrBi_2Ta_2O_9$  film 7, the heat treatment is conducted at a substrate temperature of  $600^{\circ}C$  under a reduced pressure and oxygen atmosphere.

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